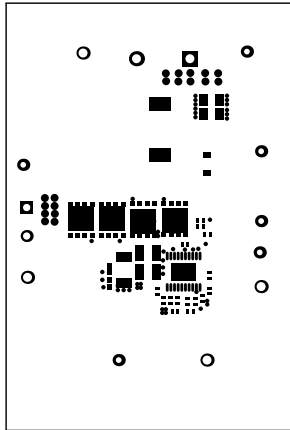
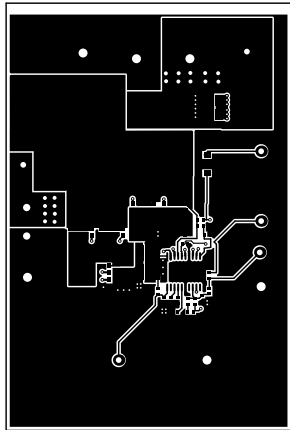


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20089	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 6/9/2017	10:31:32 AM	TEXAS INSTRUMENTS

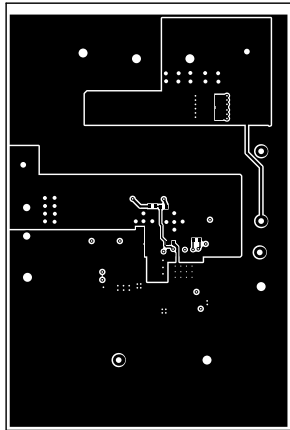


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20089	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 6/9/2017 10:31:34 AM	TEXAS INSTRUMENTS	

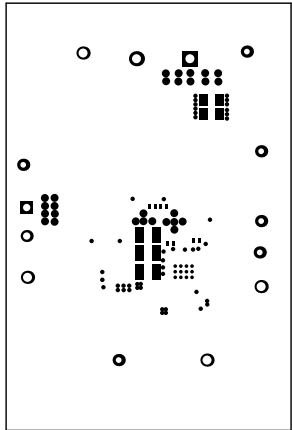


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20089	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 6/9/2017 10:31:36 AM	TEXAS INSTRUMENTS	

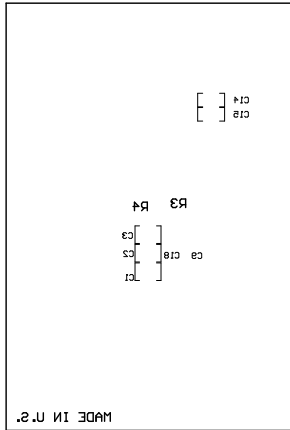
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				///
2	Top Solder	Solder Resist	0.40mil	3.5	///
3	Top Layer	Copper	2.80mil		///
4	Dielectric1	FR-4	59.20mil	4.8	///
5	Signal Layer 1	Copper	2.80mil		///
6	Dielectric 3		5.00mil	4.2	///
7	Signal Layer 2	Copper	2.80mil		///
8	Dielectric 2		10.00mil	4.2	///
9	Bottom Layer	Copper	2.80mil		///
10	Bottom Solder	Solder Resist	0.40mil	3.5	///
11	Bottom Overlay				///



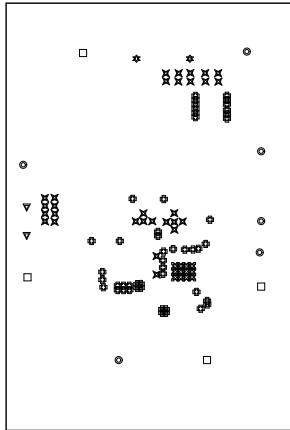
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20089	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 6/9/2017	10:31:37 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20089	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 6/9/2017 10:31:39 AM	TEXAS INSTRUMENTS	

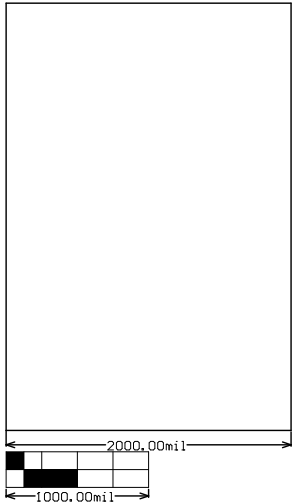


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20089	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 6/9/2017 10:31:41 AM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
⊗	12	7.87mm (0.200mm)	PTH	Round
⊕	49	12.00mm (0.395mm)	PTH	Round
⊗	29	28.20mm (0.711mm)	PTH	Round
⊕	6	40.20mm (1.016mm)	PTH	Round
▽	2	51.18mm (1.300mm)	PTH	Round
☆	2	62.99mm (1.600mm)	PTH	Round
□	4	85.00mm (1.600mm)	PTH	Round
	164 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20089	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 6/9/2017	10:31:42 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20089	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 6/9/2017	10:31:44 AM	TEXAS INSTRUMENTS

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